



<i>flow</i> PACK 1 3rd gen	1200 V / 75 A
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Features</b></div> <ul style="list-style-type: none"> <li>Compact <i>flow</i> 1 housing</li> <li>Trench Fieldstop IGBT4 Technology</li> <li>Compact and Low Inductance Design</li> <li>Built-in NTC</li> </ul> <div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Target Applications</b></div> <ul style="list-style-type: none"> <li>Motor Drive</li> <li>Power Generation</li> <li>UPS</li> </ul> <div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Types</b></div> <ul style="list-style-type: none"> <li>V23990-P820-F10</li> <li>V23990-P820-F10Y</li> </ul>	<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>flow 1 17mm housing</b></div> <div style="display: flex; justify-content: space-around; align-items: center;"> </div> <div style="background-color: #eee; padding: 2px; margin-bottom: 5px;"><b>Schematic</b></div>

## Maximum Ratings

$T_J = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
<b>Inverter Switch</b>				
Collector-emitter break down voltage	$V_{CE}$		1200	V
DC collector current	$I_C$	$T_J = T_{jmax}$ $T_s = 80^\circ\text{C}$	66	A
Repetitive peak collector current	$I_{CRM}$	$t_p$ limited by $T_{jmax}$	225	A
Power dissipation	$P_{tot}$	$T_J = T_{jmax}$ $T_s = 80^\circ\text{C}$	154	W
Gate-emitter peak voltage	$V_{GE}$		$\pm 20$	V
Short circuit ratings	$t_{SC}$ $V_{CC}$	$T_J \leq 150^\circ\text{C}$ $V_{GE} = 15\text{ V}$	10 800	$\mu\text{s}$ V
Maximum Junction Temperature	$T_{jmax}$		175	$^\circ\text{C}$

### Inverter Diode

Peak Repetitive Reverse Voltage	$V_{RRM}$		1200	V
DC forward current	$I_F$	$T_J = T_{jmax}$ $T_s = 80^\circ\text{C}$	69	A
Repetitive peak forward current	$I_{FRM}$	$t_p$ limited by $T_{jmax}$	150	A
Power dissipation	$P_{tot}$	$T_J = T_{jmax}$ $T_s = 80^\circ\text{C}$	115	W
Maximum Junction Temperature	$T_{jmax}$		175	$^\circ\text{C}$

### Thermal Properties

Storage temperature	$T_{stg}$		-40...+125	$^\circ\text{C}$
Operation temperature under switching condition	$T_{op}$		-40...+150	$^\circ\text{C}$

### Isolation Properties

Isolation voltage	$V_{is}$	$t_p = 2\text{ s}$	4000	V <sub>dc</sub>
Creepage distance			min 12,7	mm
Clearance		solder pins / Press-fit pins	12,64 / min 12,7	mm

## Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		$V_{GE}$ [V] or $V_{GS}$ [V]	$V_r$ [V] or $V_{CE}$ [V] or $V_{DS}$ [V]	$I_C$ [A] or $I_F$ [A] or $I_D$ [A]	$T_j$ [°C]	Min	Typ	Max		

### Inverter Switch

Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0024	25	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CESat}$		15		75	25 150	1,6	1,92 2,39	2,4	V
Collector-emitter cut-off current incl. Diode	$I_{CES}$		0	1200		25			0,025	mA
Gate-emitter leakage current	$I_{GES}$		20	0		25			650	nA
Integrated Gate resistor	$R_{gint}$							10		Ω
Turn-on delay time	$t_{d(on)}$	$R_{gon} = 4 \Omega$ $R_{goff} = 4 \Omega$	±15	600	75	25		165		ns
Rise time	$t_r$					150		183		
Turn-off delay time	$t_{d(off)}$					25		27		
Fall time	$t_f$					150		35		
Turn-on energy loss per pulse	$E_{on}$					25		271		
Turn-off energy loss per pulse	$E_{off}$					150		351		
Input capacitance	$C_{ies}$							83		
Output capacitance	$C_{oss}$	$f = 1 \text{ MHz}$	0	25	25			4400		pF
Reverse transfer capacitance	$C_{rss}$							290		
Gate charge	$Q_G$		±15	960	75	25		375		nC
Thermal resistance chip to heatsink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4 \text{ W/mK}$						0,62		K/W

### Inverter Diode

Diode forward voltage	$V_F$				75	25 150	1,4	1,75 1,71	2,5	V
Peak reverse recovery current	$I_{RRM}$	$R_{gon} = 4 \Omega$	±15	600	75	25		69		A
Reverse recovery time	$t_{rr}$					150		76		
Reverse recovered charge	$Q_{rr}$					25		316		
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					150		499		
Reverse recovered energy	$E_{rec}$					25		7,26		
Thermal resistance chip to heatsink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4 \text{ W/mK}$						2,61 5,34		mWs
								0,83		K/W

### Thermistor

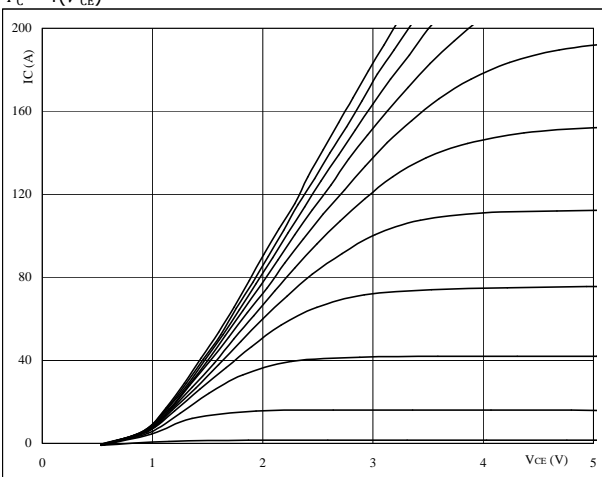
Rated resistance	$R_{25}$	Tol. ±5%				25	4,46	4,7	4,94	kΩ
Deviation of R100	$D_{R/R}$	$R_{100} = 435 \Omega$				100		2,6		%/K
Power dissipation given Epcos-Typ	$P$					25		210		mW
B-value	$B_{(25/100)}$	Tol. ±3%				25		3530		K

## Inverter Characteristics

**Figure 1** Inverter IGBT

**Typical output characteristics**

$I_C = f(V_{CE})$



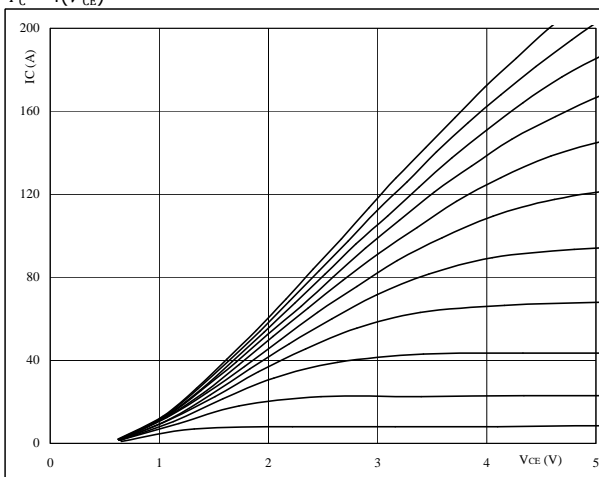
**At**

$t_p = 250 \mu s$   
 $T_j = 25 \text{ }^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

**Figure 2** Inverter IGBT

**Typical output characteristics**

$I_C = f(V_{CE})$



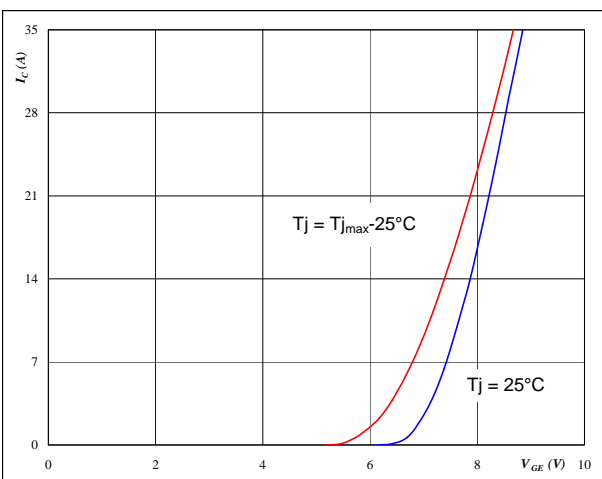
**At**

$t_p = 250 \mu s$   
 $T_j = 150 \text{ }^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

**Figure 3** Inverter IGBT

**Typical transfer characteristics**

$I_C = f(V_{GE})$



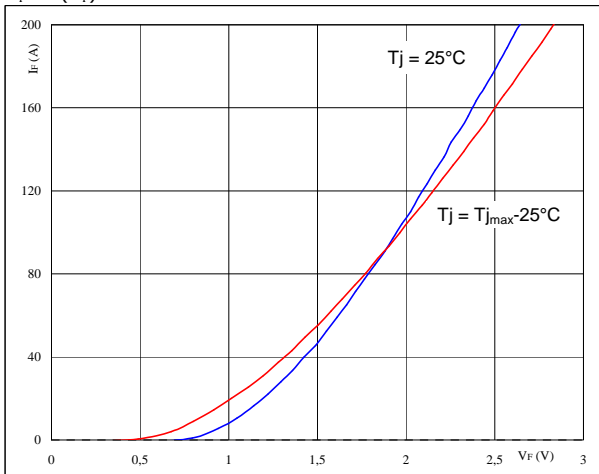
**At**

$t_p = 250 \mu s$   
 $V_{CE} = 10 V$

**Figure 4** Inverter FWD

**Typical diode forward current as a function of forward voltage**

$I_F = f(V_F)$



**At**

$t_p = 250 \mu s$

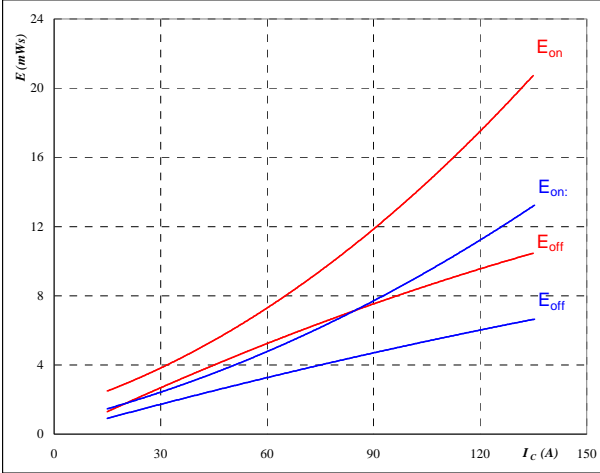


Inverter Characteristics

**Figure 5** Inverter IGBT

Typical switching energy losses  
as a function of collector current

$E = f(I_c)$



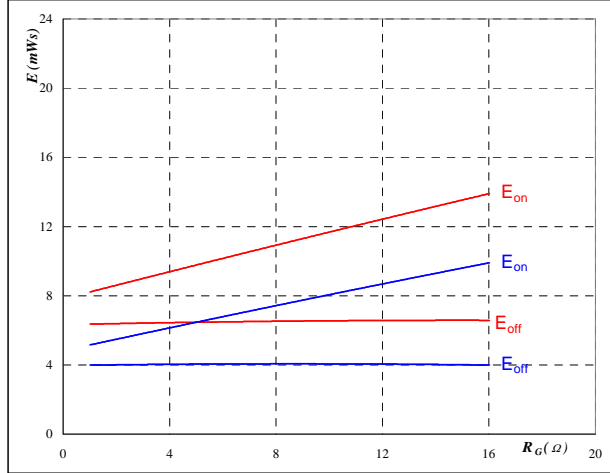
With an inductive load at

- $T_j = 25/150$  °C
- $V_{CE} = 600$  V
- $V_{GE} = \pm 15$  V
- $R_{gon} = 4$  Ω
- $R_{goff} = 4$  Ω

**Figure 6** Inverter IGBT

Typical switching energy losses  
as a function of gate resistor

$E = f(R_g)$



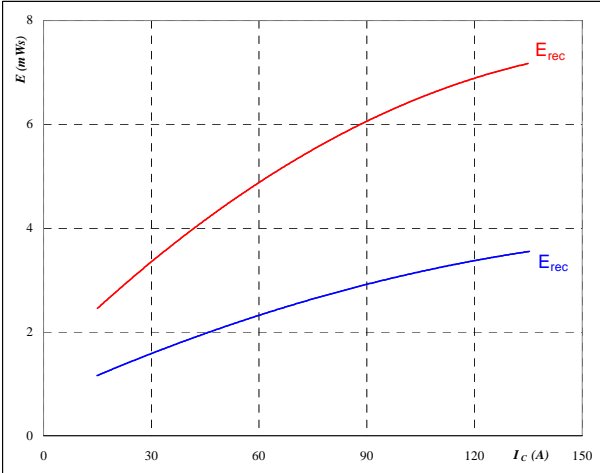
With an inductive load at

- $T_j = 25/150$  °C
- $V_{CE} = 600$  V
- $V_{GE} = \pm 15$  V
- $I_c = 75$  A

**Figure 7** Inverter FWD

Typical reverse recovery energy loss  
as a function of collector current

$E_{rec} = f(I_c)$



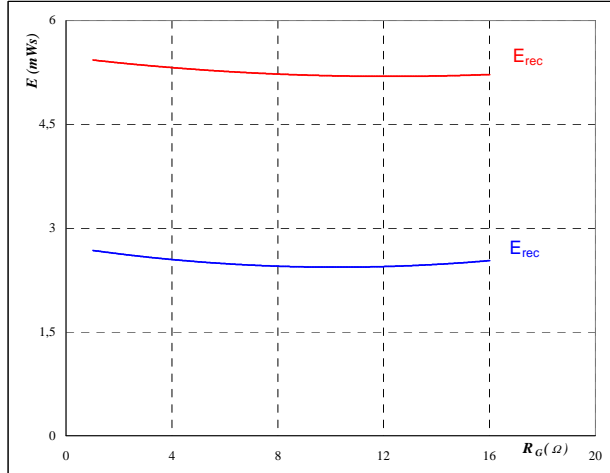
With an inductive load at

- $T_j = 25/150$  °C
- $V_{CE} = 600$  V
- $V_{GE} = \pm 15$  V
- $R_{gon} = 4$  Ω

**Figure 8** Inverter FWD

Typical reverse recovery energy loss  
as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

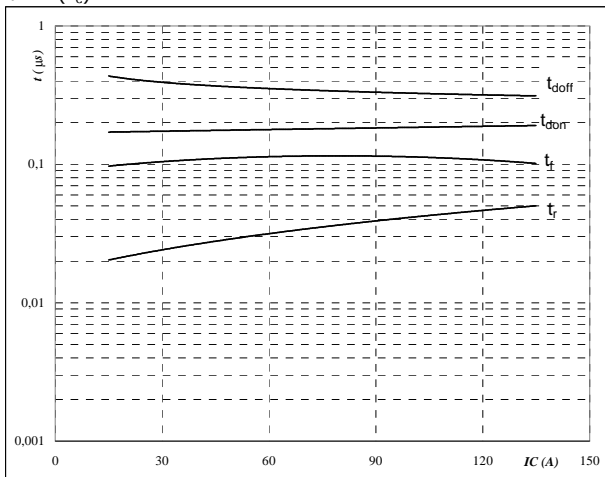
- $T_j = 25/150$  °C
- $V_{CE} = 600$  V
- $V_{GE} = \pm 15$  V
- $I_c = 75$  A

## Inverter Characteristics

**Figure 9** Inverter IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



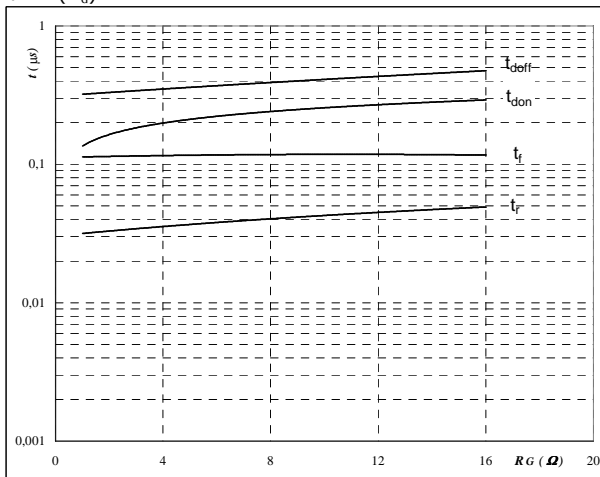
With an inductive load at

$T_j =$	150	$^{\circ}C$
$V_{CE} =$	600	V
$V_{GE} =$	$\pm 15$	V
$R_{gon} =$	4	$\Omega$
$R_{goff} =$	4	$\Omega$

**Figure 10** Inverter IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



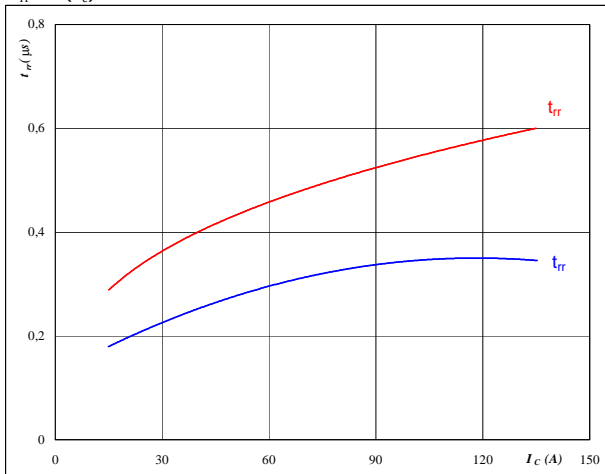
With an inductive load at

$T_j =$	150	$^{\circ}C$
$V_{CE} =$	600	V
$V_{GE} =$	$\pm 15$	V
$I_C =$	75	A

**Figure 11** Inverter FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



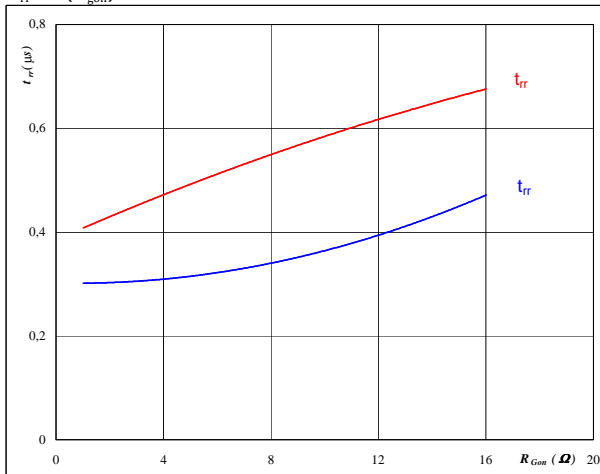
At

$T_j =$	25/150	$^{\circ}C$
$V_{CE} =$	600	V
$V_{GE} =$	$\pm 15$	V
$R_{gon} =$	4	$\Omega$

**Figure 12** Inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

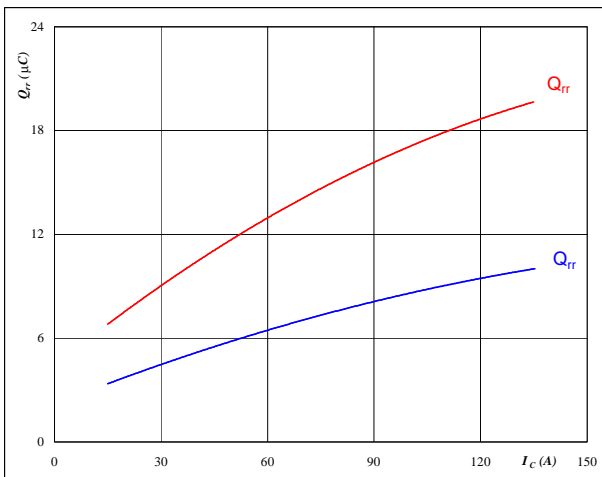
$T_j =$	25/150	$^{\circ}C$
$V_R =$	600	V
$I_F =$	75	A
$V_{GE} =$	$\pm 15$	V

## Inverter Characteristics

**Figure 13** Inverter FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_c)$$



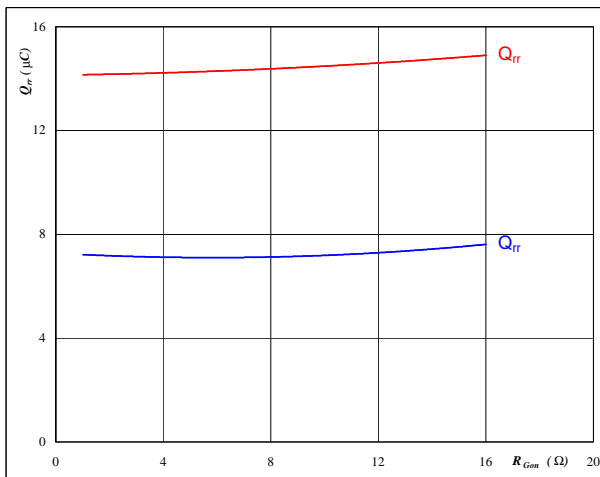
**At**

$T_j = 25/150$  °C  
 $V_{CE} = 600$  V  
 $V_{GE} = \pm 15$  V  
 $R_{gon} = 4$  Ω

**Figure 14** Inverter FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



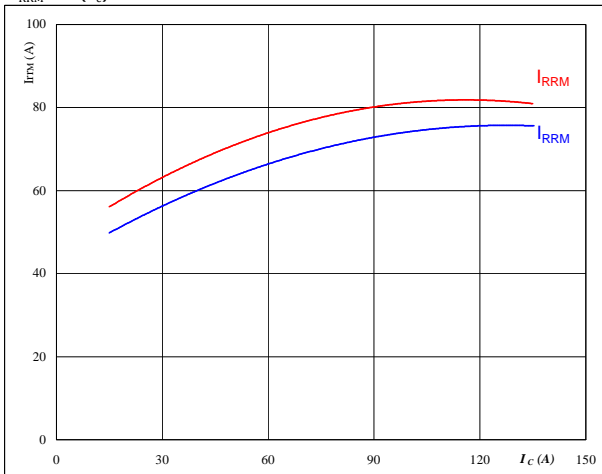
**At**

$T_j = 25/150$  °C  
 $V_R = 600$  V  
 $I_F = 75$  A  
 $V_{GE} = \pm 15$  V

**Figure 15** Inverter FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_c)$$



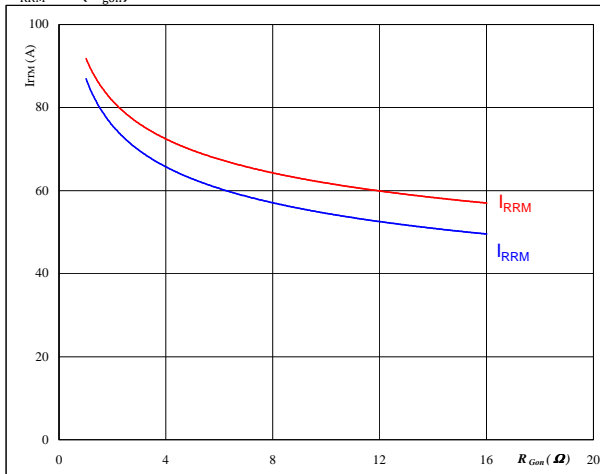
**At**

$T_j = 25/150$  °C  
 $V_{CE} = 600$  V  
 $V_{GE} = \pm 15$  V  
 $R_{gon} = 4$  Ω

**Figure 16** Inverter FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



**At**

$T_j = 25/150$  °C  
 $V_R = 600$  V  
 $I_F = 75$  A  
 $V_{GE} = \pm 15$  V

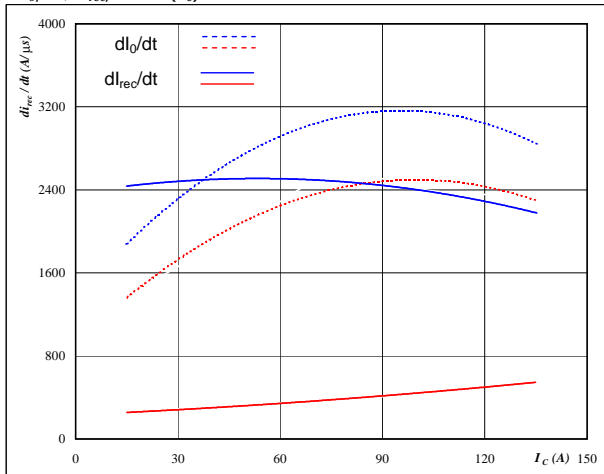


### Inverter Characteristics

**Figure 17** Inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$dI_0/dt, dI_{rec}/dt = f(I_c)$$

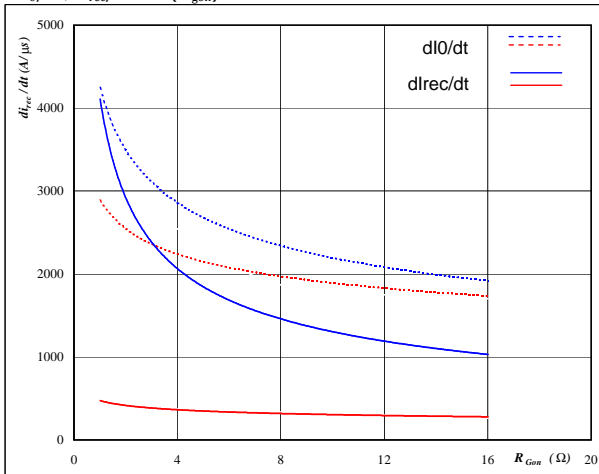


**At**  
 $T_j = 25/150 \text{ } ^\circ\text{C}$   
 $V_{CE} = 600 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $R_{gon} = 4 \text{ } \Omega$

**Figure 18** Inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$dI_0/dt, dI_{rec}/dt = f(R_{gon})$$

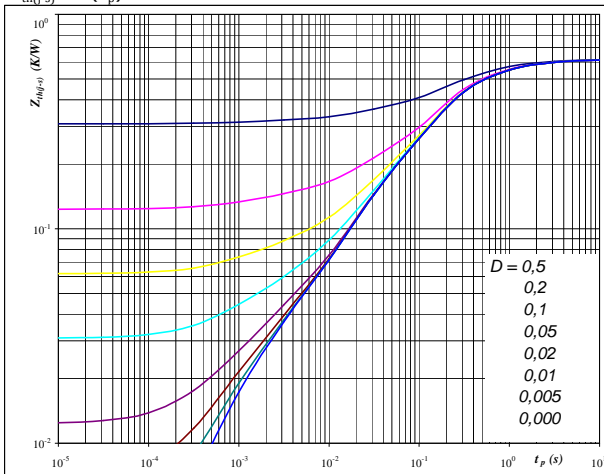


**At**  
 $T_j = 25/150 \text{ } ^\circ\text{C}$   
 $V_R = 600 \text{ V}$   
 $I_F = 75 \text{ A}$   
 $V_{GE} = \pm 15 \text{ V}$

**Figure 19** Inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



**At**  
 $D = t_p / T$   
 $R_{th(j-s)} = 0,62 \text{ K/W}$

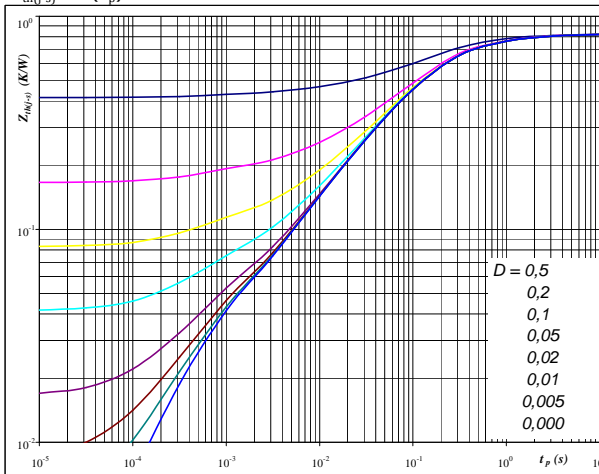
IGBT thermal model values

R (K/W)	Tau (s)
3,11E-02	5,15E+00
1,18E-01	9,17E-01
3,69E-01	1,87E-01
7,83E-02	1,99E-02
2,03E-02	1,21E-03

**Figure 20** Inverter FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



**At**  
 $D = t_p / T$   
 $R_{th(j-s)} = 0,83 \text{ K/W}$

FWD thermal model values

R (K/W)	Tau (s)
2,01E-02	9,89E+00
1,11E-01	1,17E+00
4,23E-01	1,75E-01
1,76E-01	4,11E-02
6,74E-02	7,59E-03
3,13E-02	5,41E-04

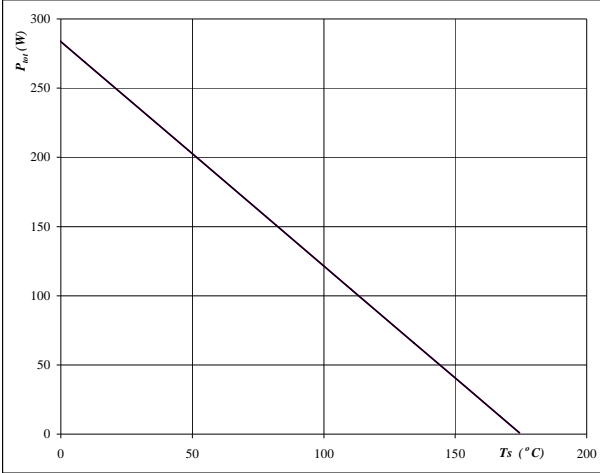


### Inverter Characteristics

**Figure 21** Inverter IGBT

**Power dissipation as a function of heatsink temperature**

$$P_{tot} = f(T_s)$$

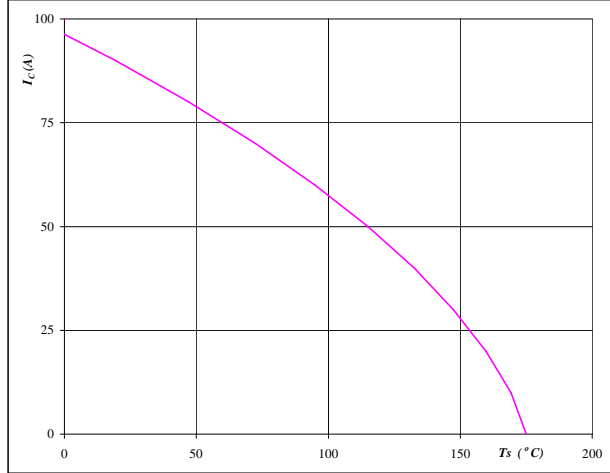


**At**  
 $T_j = 175$  °C

**Figure 22** Inverter IGBT

**Collector current as a function of heatsink temperature**

$$I_c = f(T_s)$$

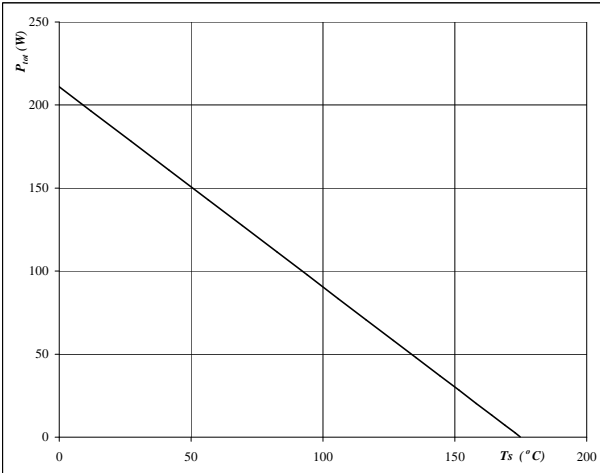


**At**  
 $T_j = 175$  °C  
 $V_{GE} = 15$  V

**Figure 23** Inverter FWD

**Power dissipation as a function of heatsink temperature**

$$P_{tot} = f(T_s)$$

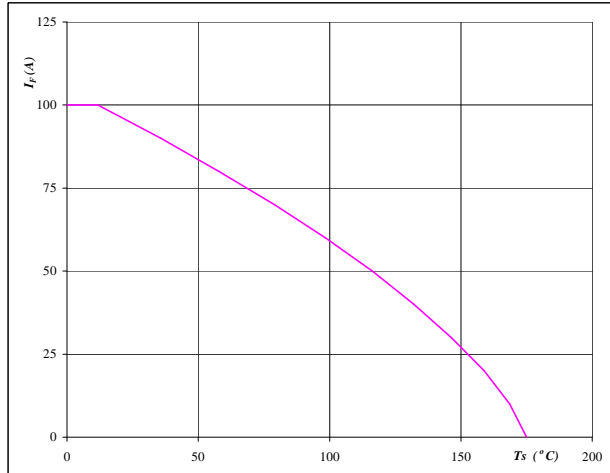


**At**  
 $T_j = 175$  °C

**Figure 24** Inverter FWD

**Forward current as a function of heatsink temperature**

$$I_F = f(T_s)$$



**At**  
 $T_j = 175$  °C



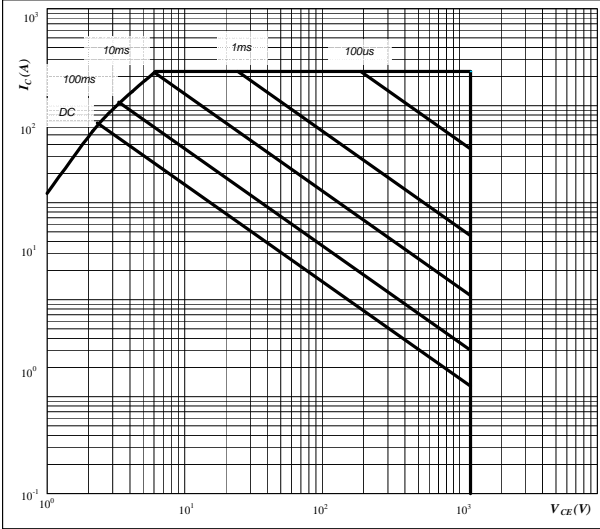


### Inverter Characteristics

**Figure 25** Inverter IGBT

Safe operating area as a function of collector-emitter voltage

$I_C = f(V_{CE})$

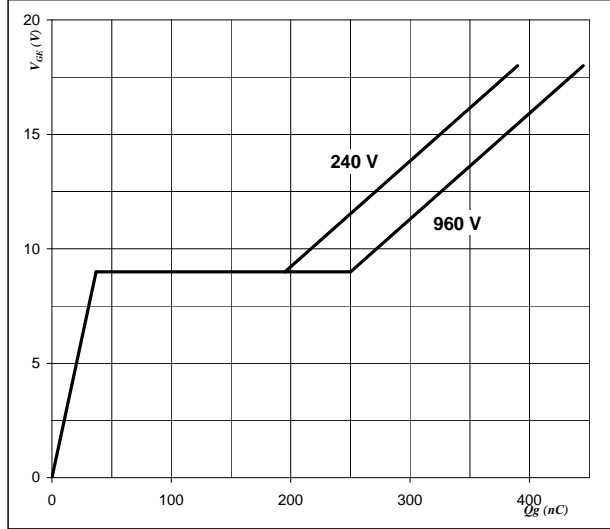


**At**  
 $D =$  single pulse  
 $T_s =$  80 °C  
 $V_{GE} =$  ±15 V  
 $T_j = T_{jmax}$

**Figure 26** Inverter IGBT

Gate voltage vs Gate charge

$V_{GE} = f(Q_g)$



**At**  
 $I_C =$  75 A

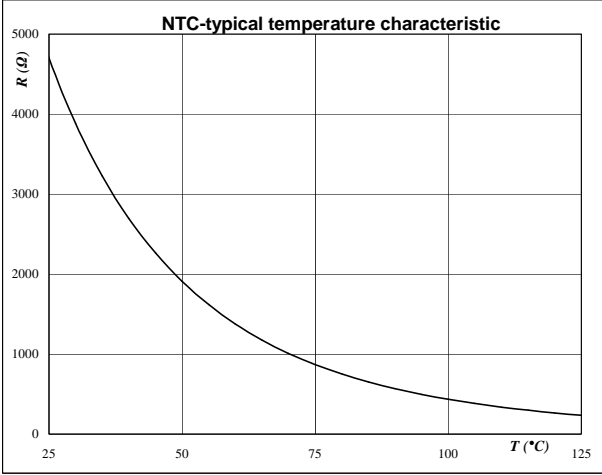


### Thermistor Characteristics

**Figure 1** Thermistor

Typical NTC characteristic  
as a function of temperature

$$R_T = f(T)$$



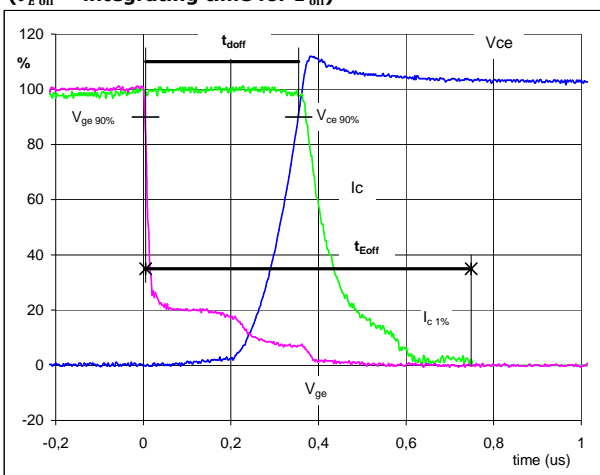
## Inverter Switching Definitions

### General conditions

$T_j$	=	150 °C
$R_{gon}$	=	4 Ω
$R_{goff}$	=	4 Ω

**Figure 1** IGBT

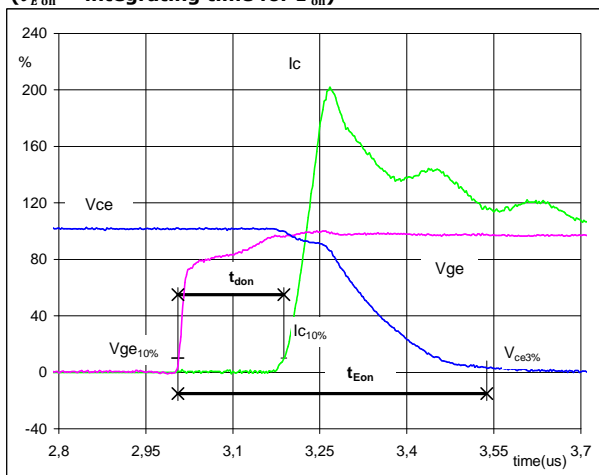
**Turn-off Switching Waveforms & definition of  $t_{doff}$ ,  $t_{Eoff}$**   
 ( $t_{Eoff}$  = integrating time for  $E_{off}$ )



$V_{GE}$ (0%) =	-15	V
$V_{GE}$ (100%) =	15	V
$V_C$ (100%) =	600	V
$I_C$ (100%) =	75	A
$t_{doff}$ =	0,35	μs
$t_{Eoff}$ =	0,74	μs

**Figure 2** IGBT

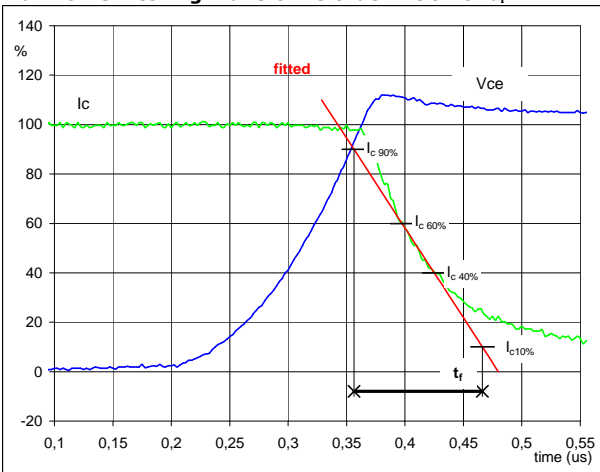
**Turn-on Switching Waveforms & definition of  $t_{don}$ ,  $t_{Eon}$**   
 ( $t_{Eon}$  = integrating time for  $E_{on}$ )



$V_{GE}$ (0%) =	-15	V
$V_{GE}$ (100%) =	15	V
$V_C$ (100%) =	600	V
$I_C$ (100%) =	75	A
$t_{don}$ =	0,18	μs
$t_{Eon}$ =	0,53	μs

**Figure 3** IGBT

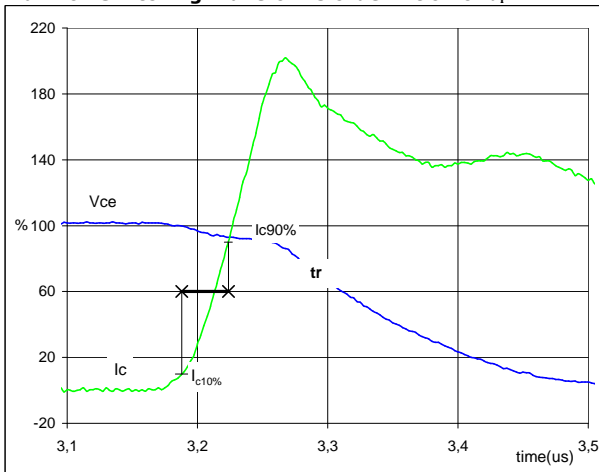
**Turn-off Switching Waveforms & definition of  $t_f$**



$V_C$ (100%) =	600	V
$I_C$ (100%) =	75	A
$t_f$ =	0,12	μs

**Figure 4** IGBT

**Turn-on Switching Waveforms & definition of  $t_r$**

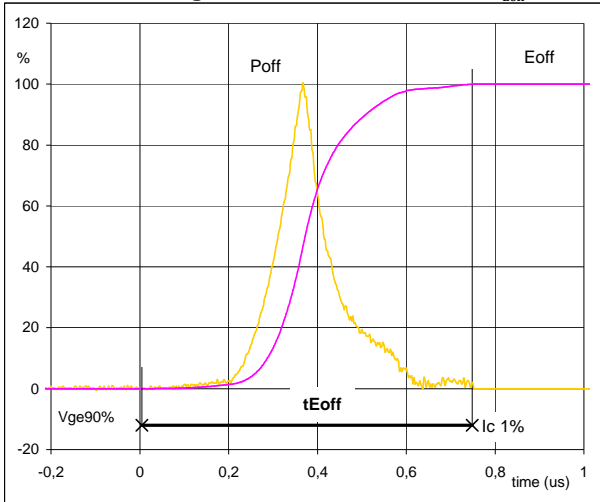


$V_C$ (100%) =	600	V
$I_C$ (100%) =	75	A
$t_r$ =	0,04	μs



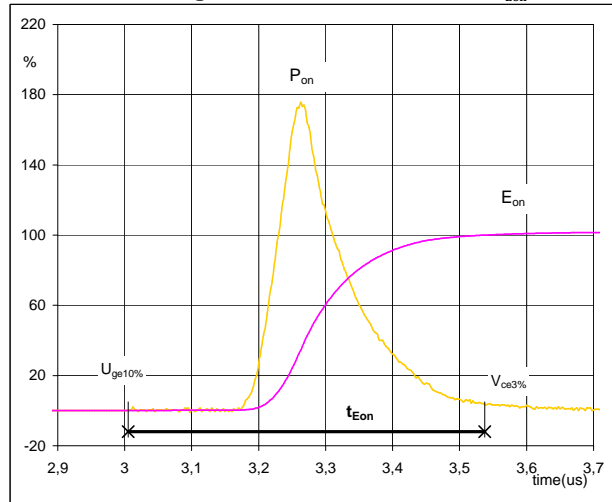
# Inverter Switching Definitions

**Figure 5** IGBT  
Turn-off Switching Waveforms & definition of  $t_{Eoff}$



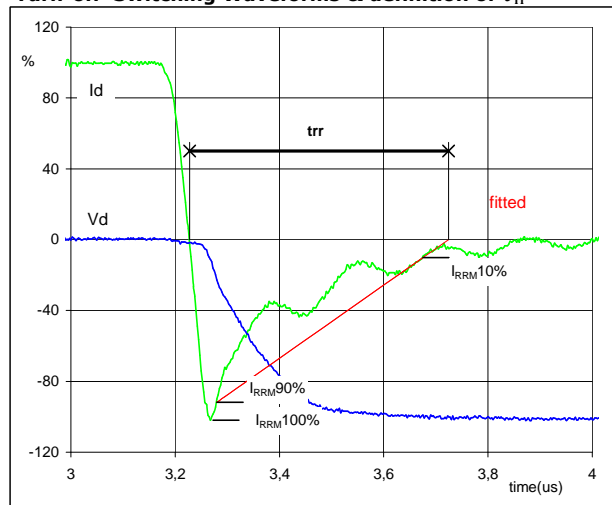
$P_{off} (100\%) = 45,22 \text{ kW}$   
 $E_{off} (100\%) = 6,48 \text{ mJ}$   
 $t_{Eoff} = 0,74 \text{ }\mu\text{s}$

**Figure 6** IGBT  
Turn-on Switching Waveforms & definition of  $t_{Eon}$



$P_{on} (100\%) = 45,22 \text{ kW}$   
 $E_{on} (100\%) = 9,44 \text{ mJ}$   
 $t_{Eon} = 0,53 \text{ }\mu\text{s}$

**Figure 7** FWD  
Turn-off Switching Waveforms & definition of  $t_{rr}$



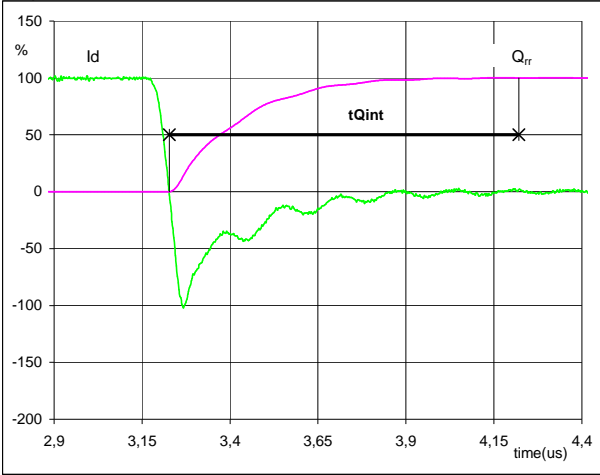
$V_d (100\%) = 600 \text{ V}$   
 $I_d (100\%) = 75 \text{ A}$   
 $I_{RRM} (100\%) = -76 \text{ A}$   
 $t_{rr} = 0,50 \text{ }\mu\text{s}$



### Inverter Switching Definitions

**Figure 8** FWD

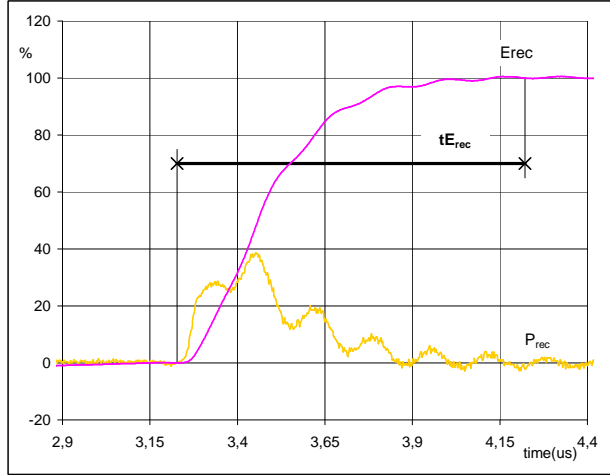
**Turn-on Switching Waveforms & definition of  $t_{Qrr}$**   
( $t_{Qrr}$  = integrating time for  $Q_{rr}$ )



$I_d$ (100%) =	75	A
$Q_{rr}$ (100%) =	14,26	$\mu\text{C}$
$t_{Qint}$ =	0,99	$\mu\text{s}$

**Figure 9** FWD

**Turn-on Switching Waveforms & definition of  $t_{Erec}$**   
( $t_{Erec}$  = integrating time for  $E_{rec}$ )



$P_{rec}$ (100%) =	45,22	kW
$E_{rec}$ (100%) =	5,34	mJ
$t_{Erec}$ =	0,99	$\mu\text{s}$



## Ordering Code and Marking - Outline - Pinout

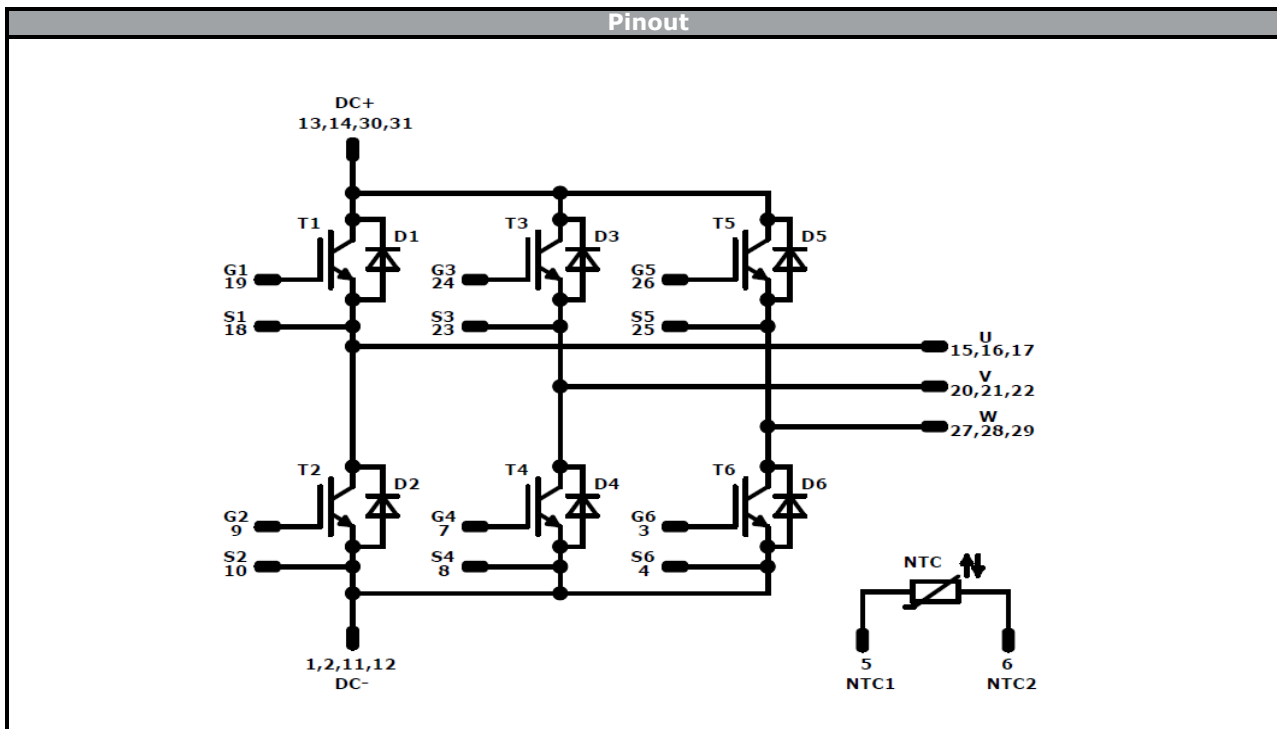
Ordering Code & Marking										
Version				Ordering Code						
without thermal paste 17mm housing, solder pins				V23990-P820-F10-PM						
with thermal paste 17mm housing, Press-fit pins				V23990-P820-F10Y-/3-/PM						
				Text	VIN	Date code	Name&Ver	UL	Lot	Serial
					VIN	WWVY	NNNNNVV	UL	LLLLL	SSSS
				Datamatrix	Name&Ver	Lot number	Serial	Date code		
					NNNNNVV	LLLLL	SSSS	WWVY		

Pin table				Outline	
Pin	X	Y	Function		
1	52,6	0	DC-		solder pins
2	49,9	0	DC-		
3	42,65	0	G6		
4	39,65	0	S6		
5	35,15	0	NTC1		
6	28,4	0	NTC2		
7	24	0	G4		
8	21	0	S4		
9	12,2	0	G2		
10	9,2	0	S2		
11	2,7	0	DC-		Press-fit pins
12	0	0	DC-		
13	0	14,65	DC+		
14	2,7	14,65	DC+		
15	0	28,6	U		
16	2,7	28,6	U		
17	5,4	28,6	U		
18	9,6	28,6	S1		
19	12,6	28,6	G1		
20	19,6	28,6	V		
21	22,3	28,6	V		
22	25	28,6	V		
23	29,7	28,6	S3		
24	32,7	28,6	G3		
25	39,7	28,6	S5		
26	42,7	28,6	G5		
27	47,2	28,6	W		
28	49,9	28,6	W		
29	52,6	28,6	W		
30	52,6	14,65	DC+		
31	49,9	14,65	DC+		

Tolerance of pinpositions: ±0,5mm at the end of pins  
 Dimension of coordinate axis is only offset without tolerance



### Ordering Code and Marking - Outline - Pinout



Identification					
ID	Component	Voltage	Current	Function	Comment
T1,T2,T3,T4,T5,T6	IGBT	1200 V	75 A	Inverter Transistor	
D1,D2,D3,D4,D5,D6	FWD	1200 V	75 A	Inverter Diode	
NTC	NTC			Thermistor	

**Packaging instruction**

Standard packaging quantity (SPQ)	<b>100</b>	>SPQ	Standard	<SPQ	Sample
-----------------------------------	------------	------	----------	------	--------

**Handling instruction**

Handling instructions for *flow* 1 packages see vincotech.com website.

**Package data**

Package data for *flow* 1 packages see vincotech.com website.

**UL recognition and file number**

This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.



<b>Document No.:</b>	<b>Date:</b>	<b>Modification:</b>	<b>Pages</b>
V23990-P820-F10x-D3-14	06 Jun. 2016	New brand, PCM Rth values	all

**DISCLAIMER**

The information, specifications, procedures, methods and recommendations herein (together "information") are presented by Vincotech to reader in good faith, are believed to be accurate and reliable, but may well be incomplete and/or not applicable to all conditions or situations that may exist or occur. Vincotech reserves the right to make any changes without further notice to any products to improve reliability, function or design. No representation, guarantee or warranty is made to reader as to the accuracy, reliability or completeness of said information or that the application or use of any of the same will avoid hazards, accidents, losses, damages or injury of any kind to persons or property or that the same will not infringe third parties rights or give desired results. It is reader's sole responsibility to test and determine the suitability of the information and the product for reader's intended use.

**LIFE SUPPORT POLICY**

Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.